SUSS MICROTEC INVESTOR PRESENTATION

May 2017

DISCLAIMER

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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SUSS MICROTEC AT A GLANCE

- **+ Global leader in manufacturing equipment for semiconductor devices**
- **+ SUSS' Equipment creates micro structures that connect micro electronic devices**
- **+ Focus on growth segments: advanced packaging, MEMS, and 2.5D / 3D Integration**
- **+ Attractive end markets: smartphones, tablets, automotive, LED, sensors, IoT, …**

- **+ Order entry 2016: € 161.1 million**
- **+ Sales 2016: € 177.6 million**
- **+ EBIT 2016: € 11.1 million**
- **+ Net Cash 2016: € 31.1 million**
- **+ Market Cap 12/31/2016: € 122 million**

MAIN PRODUCTION SITES

Germany

Sternenfels*

+ Development/production:
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
+ Production facility ~15,000 m²

Garching*

+ SUSS MicroTec HQ
+ Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
+ Production facility ~9,000 m²

USA

Corona (California)

+ Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
+ Production facility ~7,000 m²

*Production site is owned by SUSS MicroTec

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA
Order Entry 33.7 € million
Sales 25.4 € million
Employees 102

EMEA
Order Entry 38.1 € million
Sales 43.1 € million
Employees 469

ASIA
Order Entry 89.3 € million
Sales 109.0 € million
Employees 140

■ Headquarters
▨ Production
🟦 Sales

🟦 ▨ Corona, US

■ ▨ Garching, DE
▨ Sternenfels, DE
▨ Hauterive, CH
🟦 Lyon, FR
🟦 Market Rasen, UK

🟦 Singapore, SG

🟦 Yokohama, JP
🟦 Hwaseong City, KR
🟦 Shanghai, CN
🟦 HsinChu, TW

*Figures refer to the fiscal year 2016

SEGMENTS, ORDER ENTRY AND SALES FY 2016

Divisions

Photomask Equipment

Photomask Cleaning Equipment

FY 2016

Order Entry: 26.3 € million
Sales: 19.7 € million
EBIT: 1.8 € million

Lithography

Laser Processing Equipment

Exposure Systems

Coaters and Developers

Order Entry: 105.0 € million
Sales: 133.8 € million
EBIT: 13.2 € million

Bonder

Wafer Bonding Equipment

Order Entry: 18.6 € million
Sales: 14.0 € million
EBIT: -1.7 € million

SUSS MicroTec Group* FY 2016

Order Entry: 161.1 € million
Sales: 177.6 € million
EBIT: 11.1 € million
EBIT margin: 6.3%

* Including Others

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SUMMARY Q1 2017

- Strong order entry in Q1 2017 after a good Q4 2016
- Market forecasts are optimistic for FY 2017
- Successful product launch of the bond cluster XBS200
- Strategic co-operation with Kanematsu in Japan

- Order entry: € 46.0 million (+52.8% yoy)
- Sales: € 23.0 million (-16.7% yoy)
- EBIT: € -4.7 million (prev. year: € -2.0 million)
- Net Cash: € 28.0 million (+4.1% yoy)
- Market Cap April 2017: € ~200 million

SEGMENTS, ORDER ENTRY AND SALES Q1 2017

Divisions

	Photomask Equipment	Lithography	Bonder
	Photomask Cleaning Equipment	Laser Processing Equipment Exposure Systems Coaters and Developers	Wafer Bonding Equipment
Q1 2017	**Order Entry: 2.6 € million** **Sales: 3.9 € million** **EBIT: 0.03 € million**	**Order Entry: 34.1 € million** **Sales: 13.8 € million** **EBIT: -3.5 € million**	**Order Entry: 6.0 € million** **Sales: 2.6 € million** **EBIT: -0.7 € million**

SUSS MicroTec Group* Q1 2017

Order Entry: 46.0 € million
Sales: 23.0 € million
EBIT: -4.8 € million
EBIT margin: -20.9%

* Including Others

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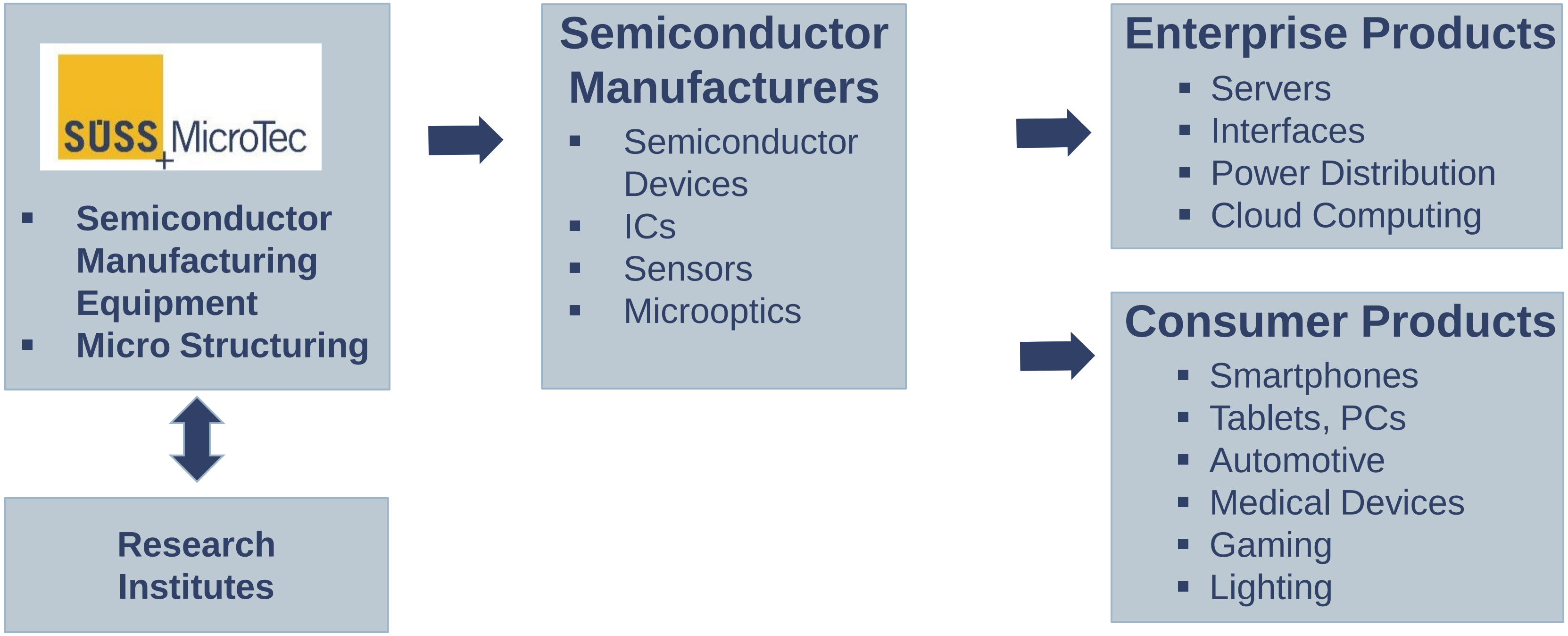
SUSS MICROTEC IN THE VALUE CHAIN



- **Semiconductor Manufacturing Equipment**
- **Micro Structuring**

Research Institutes

Semiconductor Manufacturers

- Semiconductor Devices
- ICs
- Sensors
- Microoptics

Enterprise Products

- Servers
- Interfaces
- Power Distribution
- Cloud Computing

Consumer Products

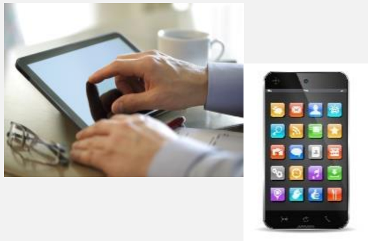
- Smartphones
- Tablets, PCs
- Automotive
- Medical Devices
- Gaming
- Lighting

- **SUSS MicroTec:**
  - Key player in leading edge semiconductor manufacturing equipment
  - Developer of highly innovative process solutions
- Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec’s equipment

MARKET DRIVERS

Connectivity & Data Processing

- Connection through apps, social media, data streaming
- Connectivity of devices, Internet of Things (IoT)
- Permanent internet connectivity provided by smartphones and tablet PCs at affordable cost
- Industry 4.0 connectivity of manufacturing units



Mobility & Automotive

- Autonomous, electric and plug in hybrid cars, E-Bikes, trains drive the need for power devices and high performance ICs at the same time
- Growing electronic content and sensors (MEMS) for autonomous cars

Energy Efficiency

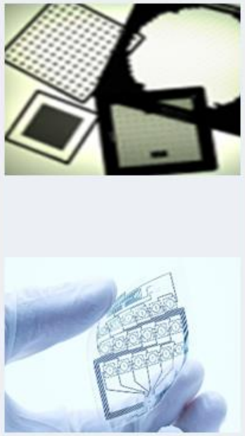
- Environmental awareness and rising energy costs drive the demand for energy efficient devices
- Energy efficiency in industrial production
- Smart energy management in household applications
- Green energy management systems

KEY MARKETS - OVERVIEW

Semiconductors

Front End Lithography

- Photomask Cleaning

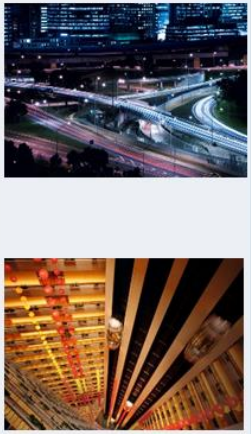


Advanced Packaging

- Micro-Bumping
- Fan-Out WLP
- Cu Pillar

Chipset Integration

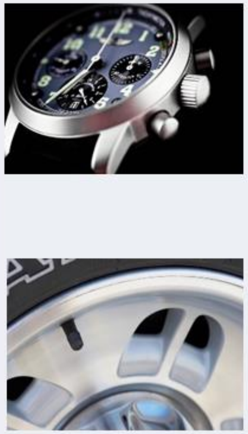
- 3D (TSV) Stacking
- 2.5D Integration



Sensors

MEMS

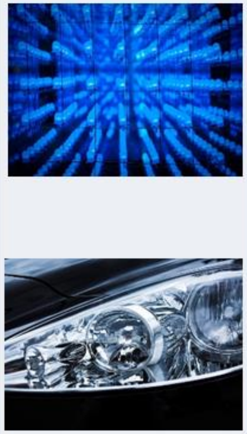
- Internet of Things
- Automotive
- Mobile Devices
- Industry 4.0
- Biomedical



Lighting

LED

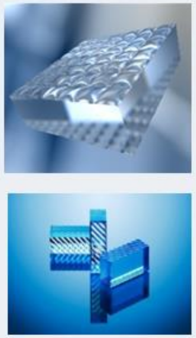
- General Lighting
- HB and UHB



Micro Optics

Advanced Optics

- Wafer Level Optics
- Fiber Optics
- Laser and Lithography Beam Shaping Optics



Micro Optical Components

Micro lens arrays
Diffractive optical elements

SEGMENTS AND PRODUCTS

Frontend

Photomask Equipment

Photomask Cleaning Equipment

MaskTrack*Pro*

Mid- and Backend

Lithography

Laser Processing Equipment

ELP300

Exposure Systems

Mask Aligner MA200/300 Gen2

Projection Scanner DSC300 Gen2

Coaters and Developers

ACS300 Gen3

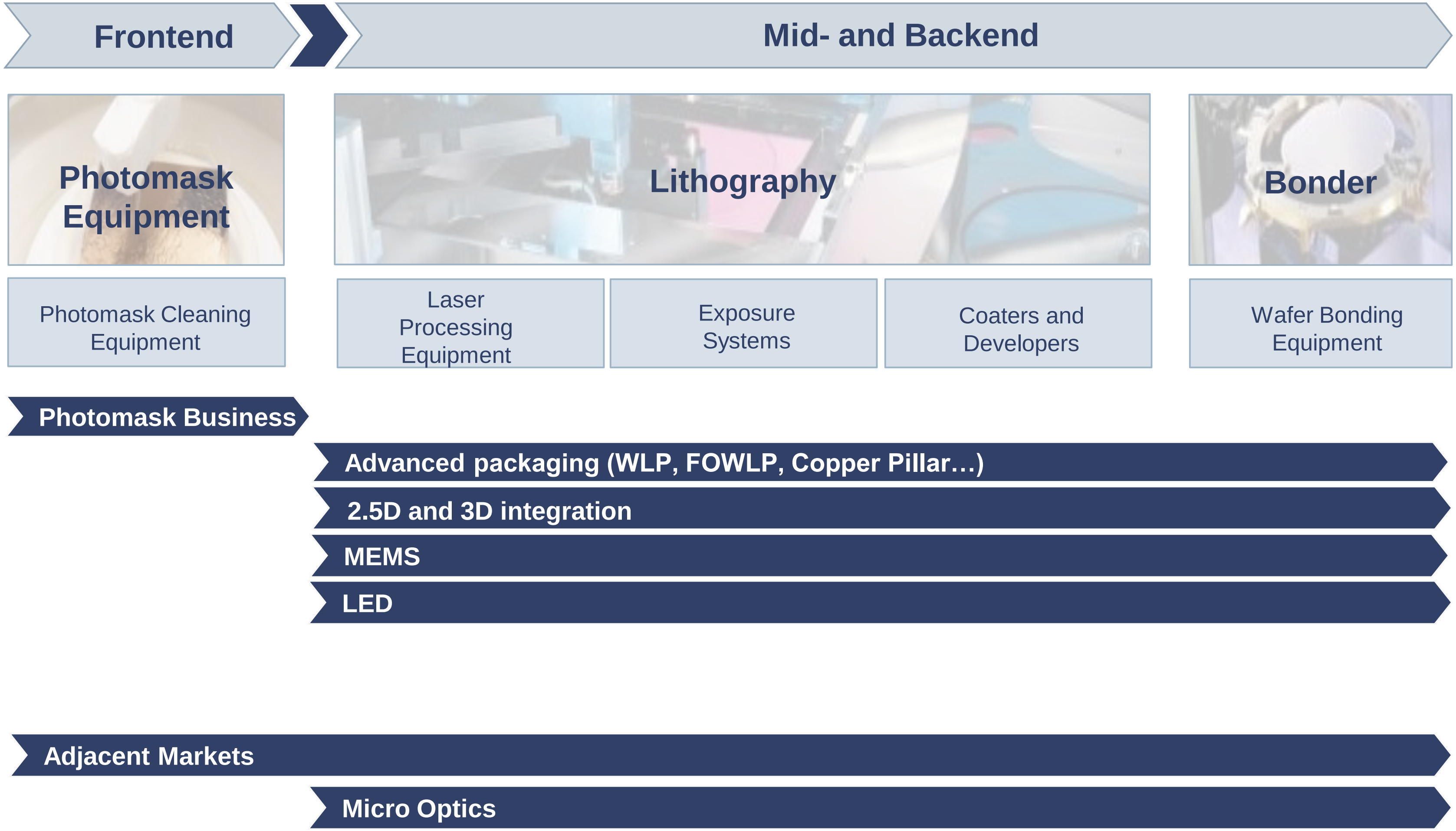
Bonder

Wafer Bonding Equipment

XBS200

XB8

SEGMENTS AND MARKETS



Frontend

Mid- and Backend

Photomask Equipment

Lithography

Bonder

Photomask Cleaning Equipment

Laser Processing Equipment

Exposure Systems

Coaters and Developers

Wafer Bonding Equipment

Photomask Business

Advanced packaging (WLP, FOWLP, Copper Pillar…)

2.5D and 3D integration

MEMS

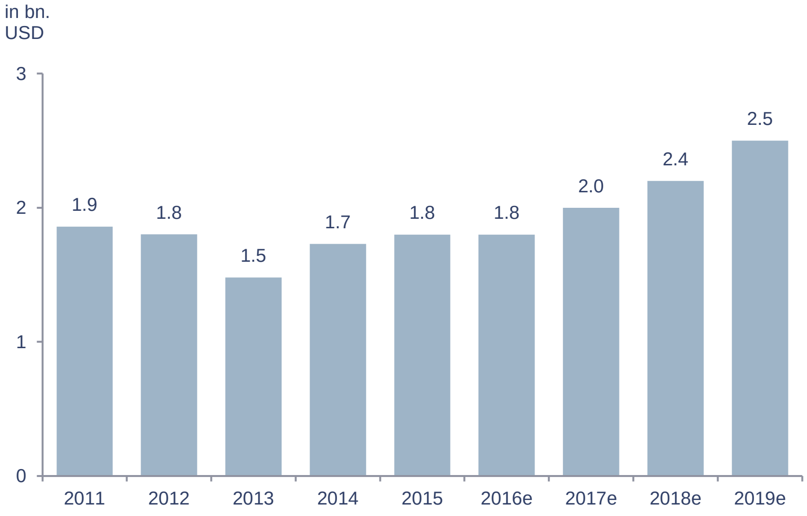
LED

Adjacent Markets

Micro Optics

KEY MARKETS – ADVANCED PACKAGING

Wafer-level packaging (WLP) and assembly equipment



Source: Gartner, January 2017

- **Attractive growth opportunities within wafer-level packaging:**
  - **Fan-out WLP**
  - **Copper pillar**
  - **Bumping**
- **Grow market share for core products in advanced packaging: coater/developer, UV-projection scanner and mask aligner**
- **Timing of new FOWLP production line investments appears to be pushing out**
- **Overall semiconductor equipment market is expected to be flat or slightly down yoy in 2016**
- **Market forecasts show a return to the growth path in WLP and assembly in 2017**

DRIVERS FOR FAN-OUT WAFER-LEVEL PACKAGING

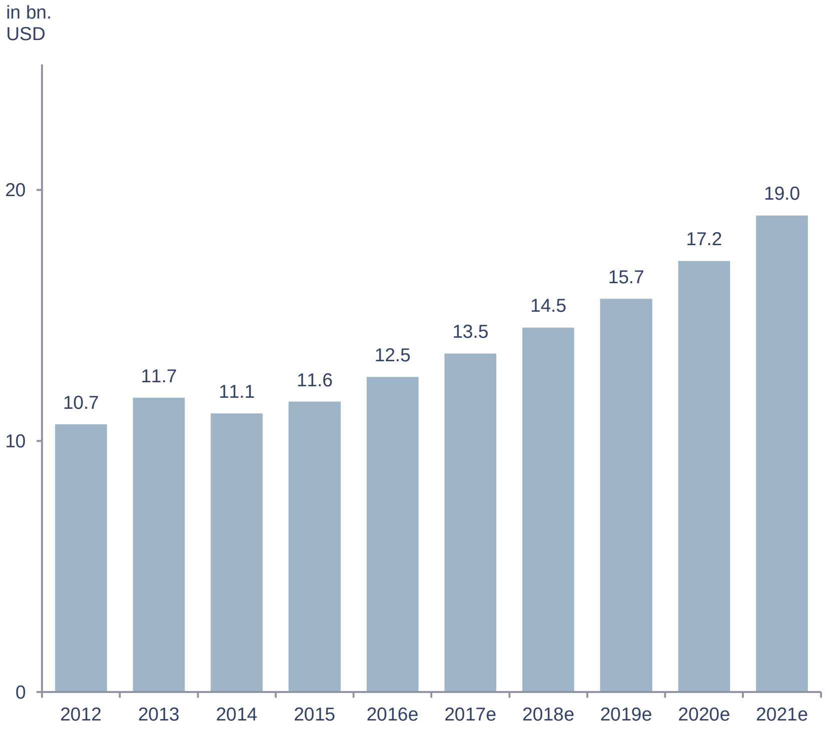
Portable electronic products are driving component packaging towards new packaging technologies for integrating multiple functions (for instance memory and application processors)

FOWLP enables:

- **Smaller form factors**
- **Split die package or multi-die package/SiP**
- **Increased I/O density** (Fine line and space (L/S))
- **Die fabrication from different technology nodes can be assembled in a single package**
- **Excellent electrical and thermal as well as high temperature warpage performance**

KEY MARKETS – MEMS

MEMS market



Source: Yole 2016

- Internet of Things (IoT)
- Smartphones and tablets
- Automotive applications
- Health/biomedical applications
- Grow market share for core products for MEMS: coater/developer, mask aligner, substrate bonder
- Market re-entry permanent bonder with new differentiated product

IC SCALING TECHNOLOGIES FROM 2D TO 3D

2D Packaging

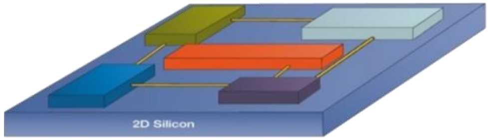
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore‘s Law
- New technologies like EUV and multiple patterning drive further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

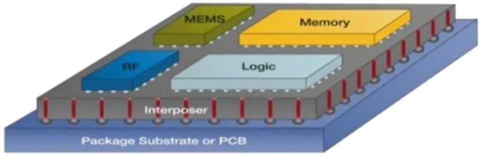
2.5D Packaging

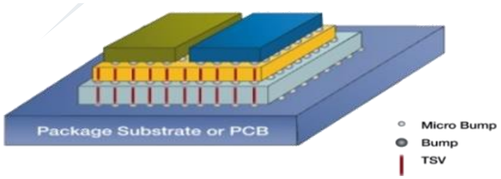
- Combining of several devices on an interposer addresses the limitations of traditional shrinking while enhancing performance
- Increased packaging density
- Reduced footprint
- Packaging becomes enabler and addresses performance slow down of Moore‘s Law

3D Integration (TSV)

- Stacking of several devices horizontally enables high performance at a low footprint
- TSV and bonded thin Si technology becomes key enabler for scaling
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption







SUSS MicroTec‘s equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 2.5D / 3D integration ("*More than Moore*")

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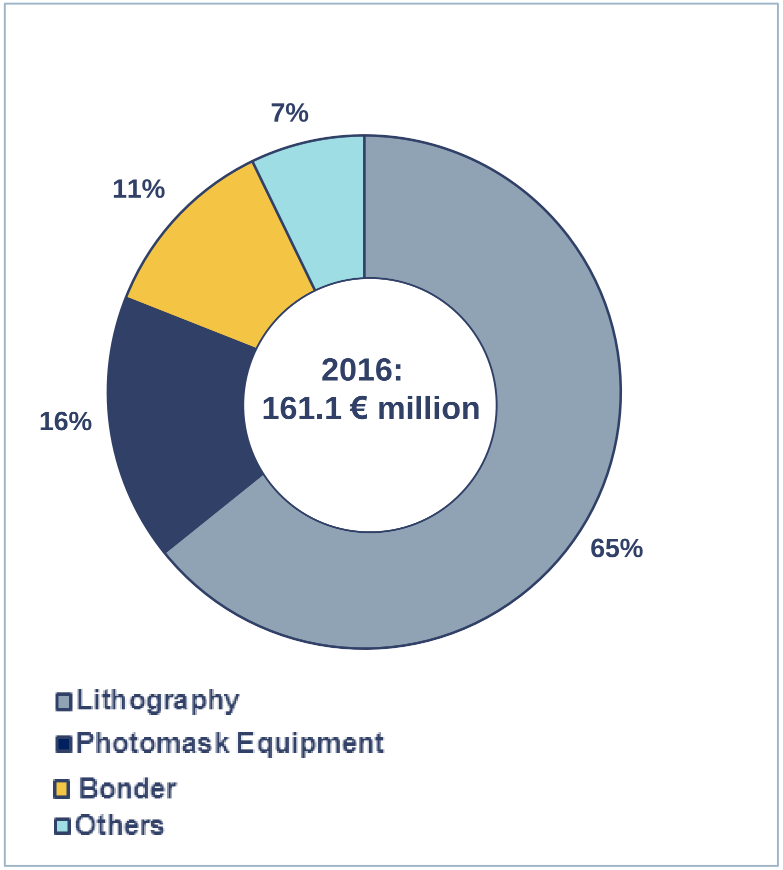
KEY FINANCIALS Q1 2017 AND FULL YEAR 2016

in € million	Q1 2017	Q1 2016	in %	2016	2015	in %
Order Intake	46.0	30.1	+52.8%	161.1	188.6	-14.6%
Order Backlog 03/31	124.5	118.8	+4.8%	101.5	117.6	-13.7%
Revenue	23.0	27.6	-16.7%	177.6	148.5	19.6%
EBIT	-4.8	-2.0	--	11.1	5.0	>100%
EBIT in % of Sales	*-20.9%*	*-7.2%*	*_-13.6%pt*	*6.3%*	*3.4%*	*2.9%pt*
Earnings after tax	-4.6	-2.5	--	5.0	0.2	>100%
EPS in €	-0.24	-0.13	--	0.26	0.01	>100%
Free Cash Flow*	-3.3	-12.9	--	-9.1	1.3	--
Net Cash	28.0	26.9	+4.1%	31.1	40.0	-22.3%
Employees 03/31	710	708	+0.3%	711	698	1.9%

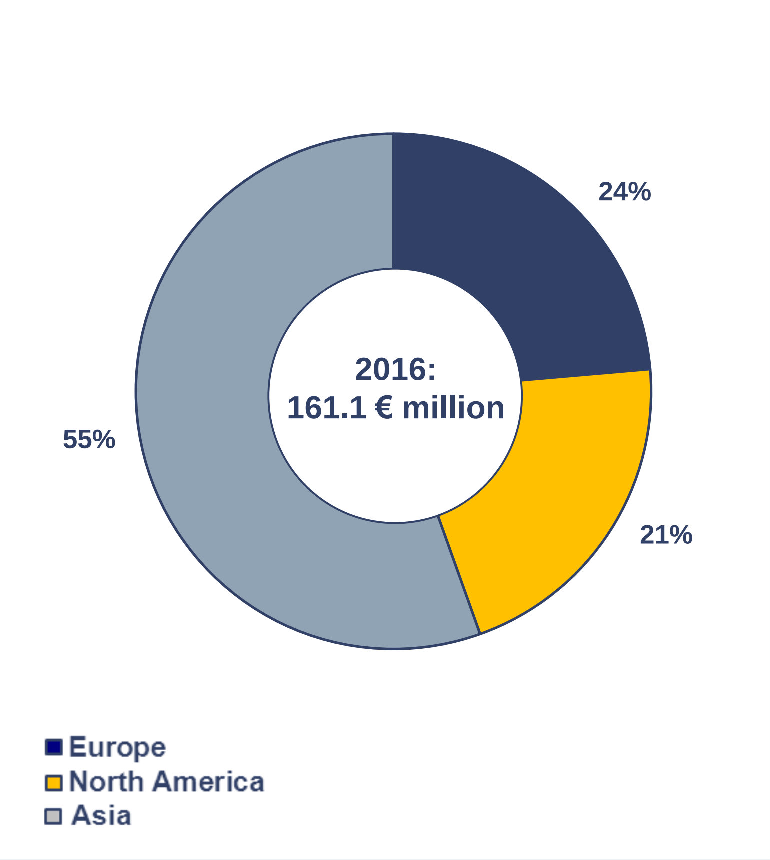
* before consideration of purchased interest-bearing securities

ORDER ENTRY AND SALES BY SEGMENT AND REGION 2016

Order Entry by Segment

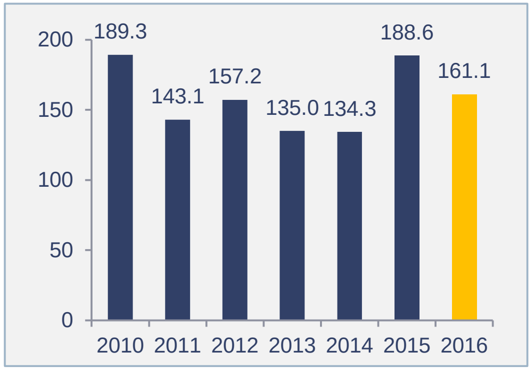


Order Entry by Region

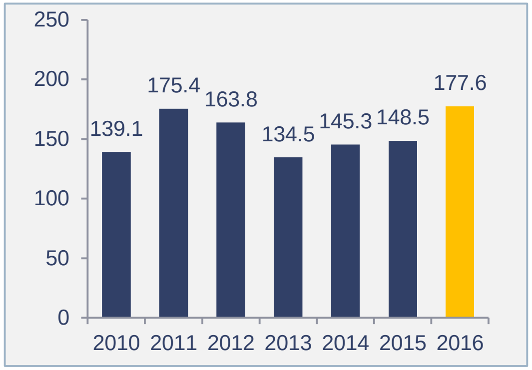


LONG TERM BUSINESS DEVELOPMENT – P&L KEY FIGURES

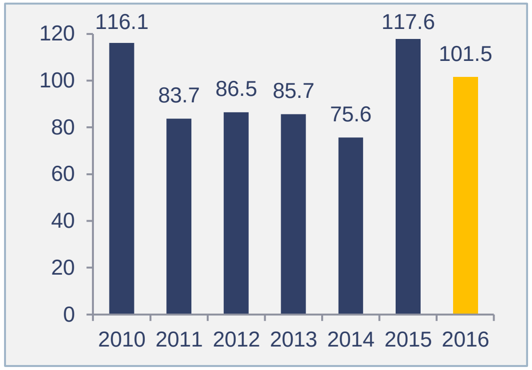
Order Entry in € million



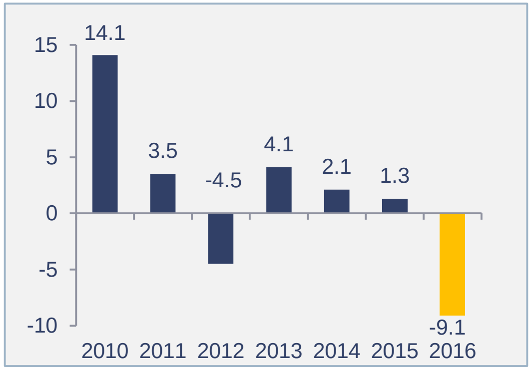
Sales in € million



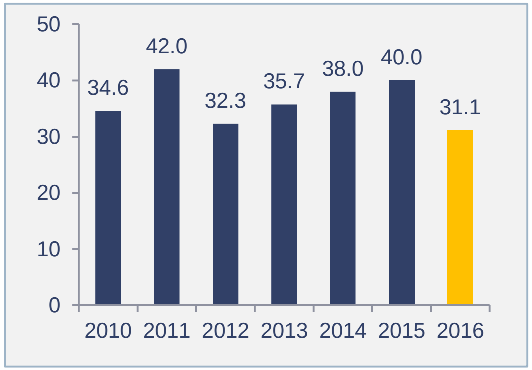
Order Backlog in € million



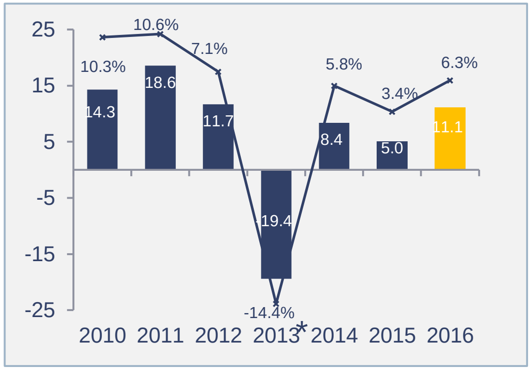
Free Cash Flow in € million



Net Cash in € million

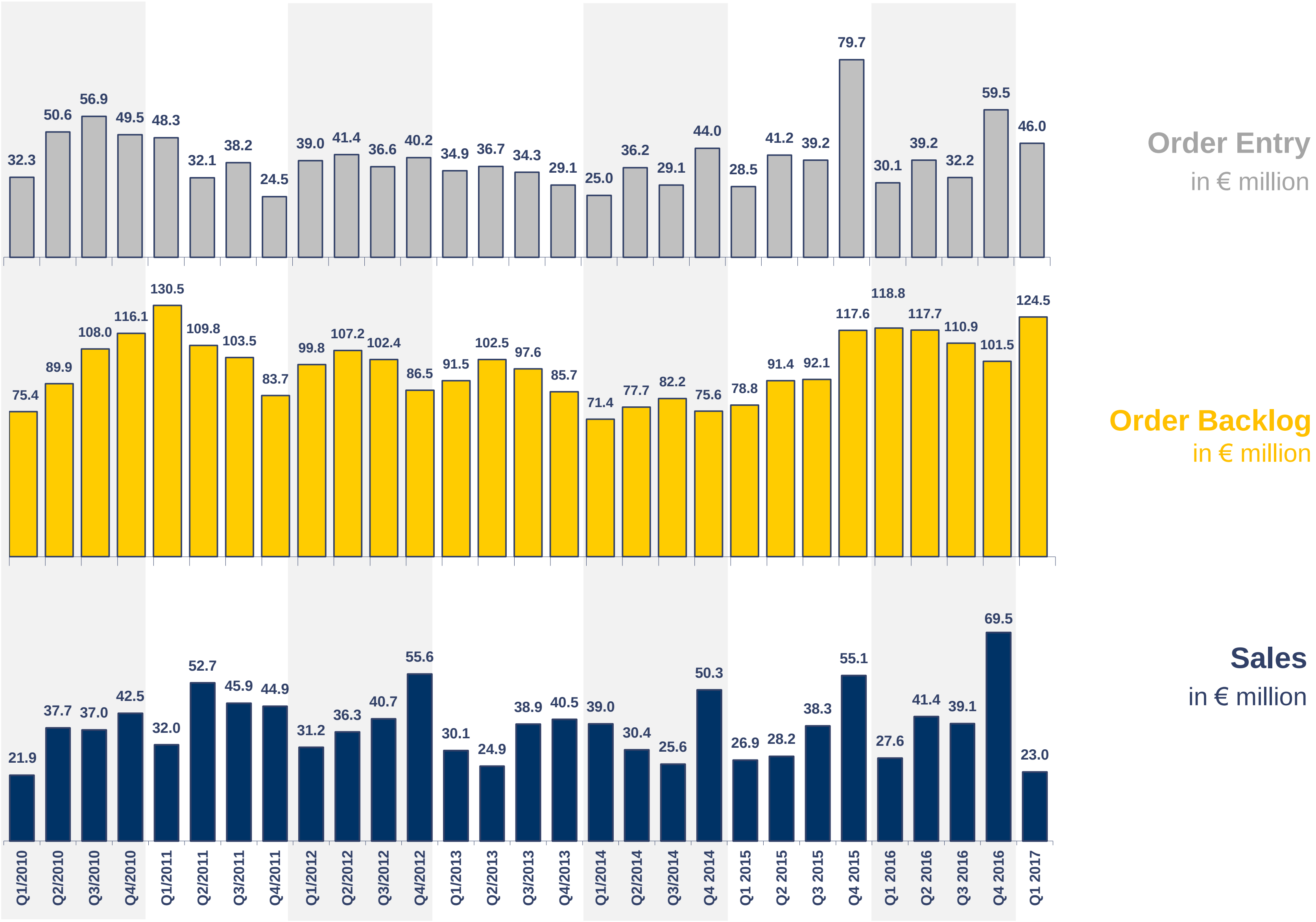


EBIT in € million

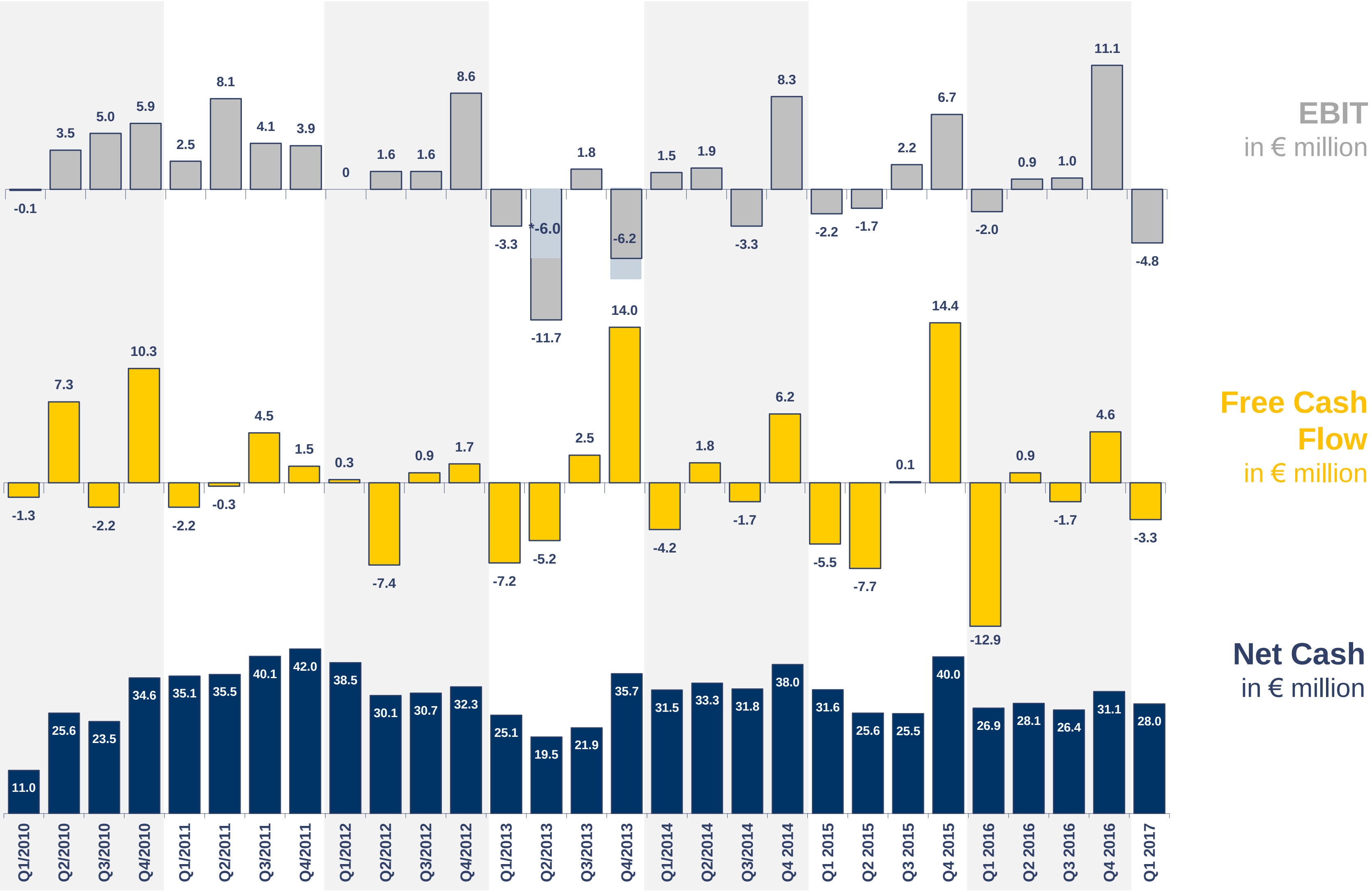


* Including a -13.2 € milion one-off effect from restructuring of the product line permanant bonding (-0,69 € per share)

LONG TERM BUSINESS DEVELOPMENT BY QUARTER



EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



* one-off effect from restructuring the product line permanent bonding

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ROADMAP TARGETS

Short-term

- Grow market share for core products in all market segments
- Traction for new advanced lithography products from SUSS MicroTec Photonic Systems
- Stabilize Company at positive EBIT and cash generation, continue revenue growth:
  - Gross margin 30-35% ✓

Mid-term

- Focused product portfolio
- Positive EBIT from Bonder Division and Photonic Systems
- Successful new adjacent market entries (leverage existing technologies to grow SAM)
- Continue revenue growth at positive EBIT and cash generation:
  - Sales of >200M
  - Gross margin >35% ✓ (excluding Photonic Systems)
  - EBIT margin >5% ✓

Long-term

- Continue revenue growth at positive EBIT and cash generation:
  - Sales of >200M
  - Gross margin >35%
  - EBIT margin 10%

OUTLOOK

Market Outlook

- Gartner increased its estimates regarding growth in the semiconductor business in 2017 from +7.2% to +12.3%
- This would mark a new record level of 386 bn $ (2016: 339.7 bn $)
- Market growth will be driven by automotive and industrial applications, the memory segment and the Internet of Things
- Semi still expects the semiconductor equipment market to grow by +9.2% in 2017
- Wafel-level-packaging and assembly equipment market is expected to grow by 10.7% in 2017 after 3.9% in 2016 (Gartner)
- Yole expectes MEMS-market CAGR 2015 – 2021 of 13% (unit growth)

SUSS MicroTec Outlook

- FY 2017: Sales € 170 – 180 million
EBIT € 13 – 17 million
- Q2 2017: Order entry € 35 - 45 million

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INVESTOR RELATIONS INFORMATION

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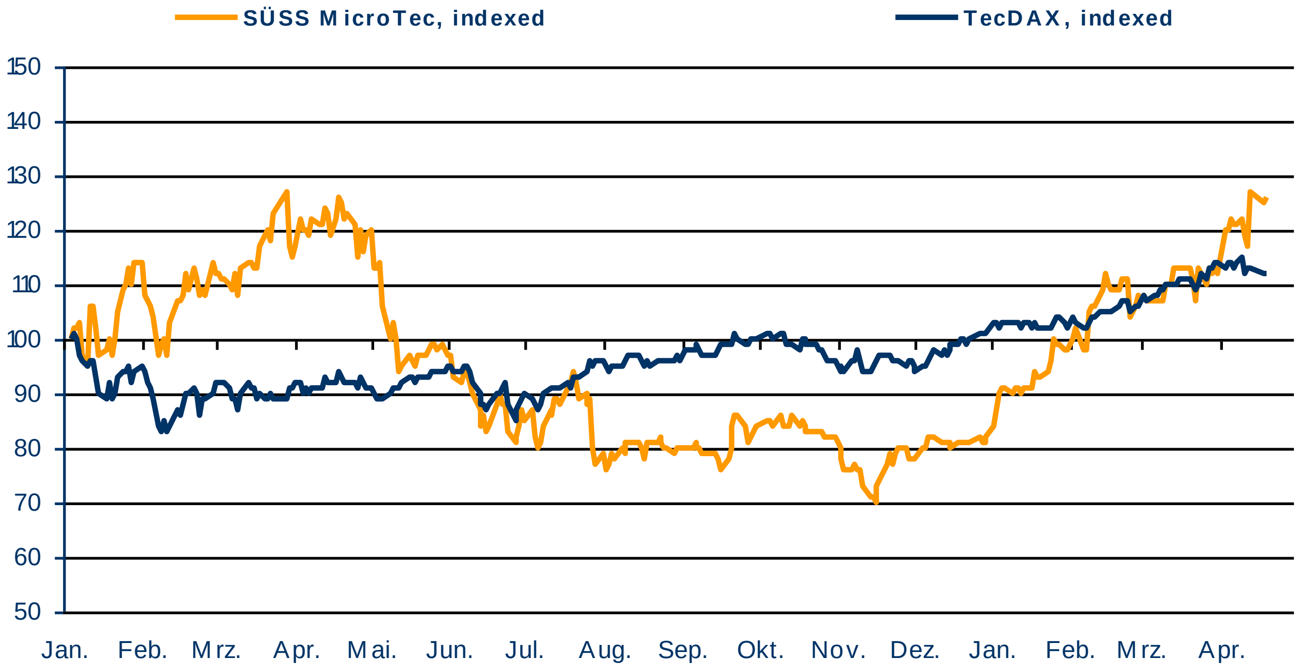
Financial Calendar 2017

Annual Report 2016	30 Mar
Quarterly Report 2017	4 May
Annual General Meeting 2017, Munich	31 May
Interim Report 2017	10 Aug
Nine-month Report 2017	9 Nov

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SUSS MicroTec Share at January 2, 2016: 4.88 €)

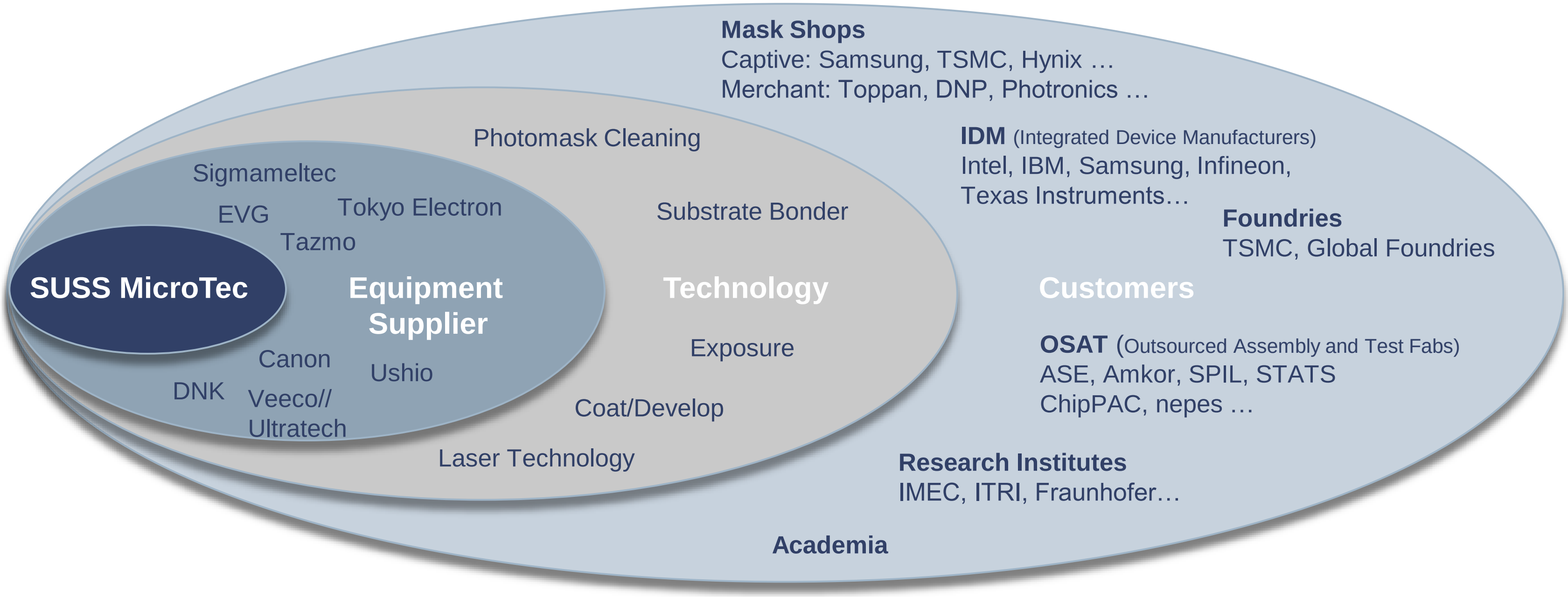


Major Shareholders:

Sycomore	5.2%
Henderson	5.1%
Universal	5.1%
Lupus Alpha	3.2%
Dimensional	3.0%

Average daily trading volume January 2016 – April 2017: ~ 160.000

MAIN COMPETITORS AND PEER GROUP



SUSS MicroTec

Equipment Supplier

Sigmameltec

EVG

Tokyo Electron

Tazmo

Canon

Ushio

DNK

Veeco//
Ultratech

Technology

Photomask Cleaning

Substrate Bonder

Exposure

Coat/Develop

Laser Technology

Customers

Mask Shops
Captive: Samsung, TSMC, Hynix …
Merchant: Toppan, DNP, Photronics …

IDM (Integrated Device Manufacturers)
Intel, IBM, Samsung, Infineon,
Texas Instruments…

Foundries
TSMC, Global Foundries

OSAT (Outsourced Assembly and Test Fabs)
ASE, Amkor, SPIL, STATS
ChipPAC, nepes …

Research Institutes
IMEC, ITRI, Fraunhofer…

Academia

Peer Group	
BE Semiconductor:	equipment for leadframe, substrate and WLP applications (die attach, wire-bonding, plating), target markets include electronics, computer, automotive, industrial, LED and solar energy
Veeco/Ultratech:	steppers for the semiconductor market, advanced packaging, nanotechnology, laser processing (LSA)
Kulicke & Soffa:	design and manufacture of equipment for semiconductor, LED and electronic assembly (wire-bonding, advanced packaging)
Rudolph Tech:	equipment and software solutions for macro defect inspection, probe card test and analysis, thin film metrology, advanced packaging lithography systems (steppers)
EV Group:	equipment for wafer-bonding, lithography/nanoimprint lithography (NIL), metrology, photoresist coating, cleaning and inspection for the target markets: advanced packaging, compound semiconductor and silicon-based power devices, MEMS, nanotechnology and SOI